



ROSIN FOAM FLUX

PC 26

GENERAL DESCRIPTION

PC26 Liquid Flux is an activated, non-corrosive, rosin-based liquid flux which has been specially formulated to reduce icicles and bridging to a minimum on printed circuit boards. PC26 Liquid Flux has a low solids content and leaves dry and non-sticky boards after soldering. The minimal residues left on the boards are hard, protective and non-corrosive.

APPLICATIONS

PC26 Liquid Flux can be used for wave soldering of all printed circuit boards to give fast production speeds and reliable soldering. Because of its special action of suppressing icicles and bridging it will be found that soldering machine settings are not so critical as with other rosin-based fluxes.

PROCEDURE

PC26 Liquid Flux may be applied by foam, wave, brush, roller, spray or dip. When soldering printed circuits it is important to dry off most of the solvent before soldering. The flux should be dried to a sticky state after pre-heating. In small production processes where the board is hand brushed, sprayed or dipped, either force dry to a sticky state or leave for about 10 minutes at room temperature.

FLUX CONTROL

The concentration of all rosin-based liquid fluxes increases during use because of loss of solvent. The concentration of PC26 Liquid Flux can easily be maintained by replacing the lost solvent periodically with PC70 Multicore Thinners. As the thinners are slowly added to the flux bath, the specific gravity of the modified solution is monitored by using a hydrometer until it reaches 0.825.

FLUX RESIDUES

Since the residues of PC26 Liquid Flux are minimal and non-corrosive, their removal after soldering may not be considered as necessary as with other rosin-based fluxes. If removal of all residues is preferred they may be removed most efficiently with PC81 Multicore Solvent Cleaner and Rosin Residue Remover or PC86 Multicore Biodegradable Rosin Residue Remover.

PROPERTIES

Specific Gravity at 25°C (77°F)	0.823 ± 0.002
Solids Content w/w	15%
% Halide (on solids)	0.5% Max.
Flashpoint (Abel closed cup)	12°C (53°F)
Boiling Point of Solvent	82°C (179°F)
Electrical resistance of flux residue	Greater than 1000 megohms over 1/2" (1.25cm) in accordance with Ministry of Defence Spec. D.T.D. 599A.

SPECIFICATION

PC26 Multicore Rosin Foam Flux is designed to meet and exceed the requirements of British Ministry of Defence Specification D.T.D. 599A for non-corrosive rosin-based liquid fluxes. It has also received official approval from British Telecom.

HEALTH AND SAFETY

The following is intended for general guidance only. A more comprehensive Health and Safety Data Sheet is available. Multicore Rosin-based Liquid Fluxes are safe to use provided that certain precautions are observed.

Fumes, Vapours and Precautions: Excessive inhalation of the solvent vapour, which may cause headache, dizziness and nausea and the flux fumes given off at soldering temperature, which are irritating to the throat and respiratory organs, should be avoided. The TLV of the solvent is 400 ppm. The TLV of rosin-based flux fumes measured as formaldehyde is 0.1 mg/m³. Multicore Rosin-based Liquid Fluxes must always be used in well ventilated areas. Suitable fume extraction equipment should be used to extract the solvent vapours and flux fumes away from the operators.

Protection and Hygiene: Suitable protective clothing should be worn to prevent the material from coming in contact with the skin and eyes. If the material comes in contact with the skin, the affected area should be cleaned with PC70 Multicore Thinners or a resin removing cream followed by washing with soap and warm water. If the material comes in contact with the eyes, they should be irrigated thoroughly with running water for at least 10 minutes. In severe cases medical attention should be sought. Eating and drinking should not be permitted in the working area and hands should be washed with soap and warm water before eating.

Fire Hazards and Precautions: Multicore Rosin-based Liquid Fluxes contain a highly flammable solvent with a flash point of 12°C (53°F). The material must not be used near naked flames or non-flameproof electrical equipment. Smoking must not be permitted in the working area. Carbon dioxide, foam or dry powder extinguishers should be used if the material catches fire. Storage of the material must comply with the relevant national regulations for highly inflammable liquids.

Spillage and Waste Disposal: Spillage of the material should be mopped up with sand or sawdust. Waste material should be stored in closed containers and disposed of in accordance with local regulations.



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